



Features 特性

- Low Thermal Resistance 低热阻
- Low Viscosity 低粘度
- High Reliability 高可靠性
- Screen Printing 丝网印刷

Applications 产品应用

- Laptop CPU 笔记本电脑 CPU
- Communication equipment 通讯设备
- Power supply controller 电源控制系统
- ADAS 智能驾驶系统

Thermal TIG0601 是一种具有低粘度，低热阻的导热硅脂，可采用印刷或点胶的方式涂覆在发热器件或者散热器表面，装配后可以跟界面形成良好的润湿，降低系统的接触热阻，从而提高散热效率。

Thermal TIG0601 is a kind of thermal grease material with low viscosity and low thermal resistance. The material can be applied on heating devices and heat spreader surfaces by printing or dispensing. Due to good wetting between the interfaces after assembly, the contact thermal resistance will be substantially reduced to improve heat dissipation efficiency.

Property 特性	Typical Value 典型值	Unit 单位	Test Method 测试方法
Composition 主要成分	Silicone Filled with Thermal Powder 硅胶&导热粉体		—
Color 颜色	Gray 灰色	—	Visual 目视
Thermal Conductivity 导热系数	6.0	W/m·K	ASTM D5470
Thermal Resistance 热阻	0.088 @ 40Psi	°C.cm ² /W	ASTM D5470
Bond-line Thickness (BLT) 界面结合厚度	30	μm	—
Viscosity 粘度@1s ⁻¹	620	Pa.s	ASTM D2196
Density 密度	3.30	g/cm ³	ASTM D792
Temperature Range 耐温范围	-40 - 150	°C	—
Breakdown Voltage 击穿强度	≥6	KV/mm	ASTM D149
RoHS Compliance 合规性	YES	—	—
Shelf Life 保存期	6	month	25±5°C, ≤50% RH

All technical information stated in this technical data have been confirmed that all the technical parameters are reliable after harsh testing and evaluation of the products. Before you use our products, please carefully evaluate and decide whether the product meets your requirement and you need to take all the risks and responsibilities to use.

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